

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5195203

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
SEUNGWOO HONG	10/11/2018
JONG IL PARK	10/11/2018
HEECHANG OH	10/11/2018
YEONGSEOP PARK	10/11/2018
DONG HEE HAN	10/11/2018
HYUNGBOK LEE	10/11/2018

**RECEIVING PARTY DATA**

<b>Name:</b>	HYUNDAI MOTOR COMPANY
<b>Street Address:</b>	12, HEOLLEUNG-RO, SEOCHO-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	06797
<b>Name:</b>	KIA MOTORS CORPORATION
<b>Street Address:</b>	12, HEOLLEUNG-RO, SEOCHO-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	06797

**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	16158515

**CORRESPONDENCE DATA****Fax Number:** (312)321-4299*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***Phone:** 312-321-4200**Email:** usassignments@brinksgilson.com, rpetitt@brinksgilson.com,  
jjang@brinksgilson.com, sdamron@brinksgilson.com**Correspondent Name:** BRINKS GILSON & LIONE**Address Line 1:** 455 N. CITYFRONT PLAZA DRIVE**Address Line 2:** SUITE 3600**PATENT**

<b>Address Line 4:</b>	CHICAGO, ILLINOIS 60611
<b>ATTORNEY DOCKET NUMBER:</b>	15438-704
<b>NAME OF SUBMITTER:</b>	SEUNG-HYUN JANG
<b>SIGNATURE:</b>	/Seung-Hyun Jang/
<b>DATE SIGNED:</b>	10/18/2018
<b>Total Attachments: 7</b> source=15438-704_Comb_Asmt_Dec#page1.tif source=15438-704_Comb_Asmt_Dec#page2.tif source=15438-704_Comb_Asmt_Dec#page3.tif source=15438-704_Comb_Asmt_Dec#page4.tif source=15438-704_Comb_Asmt_Dec#page5.tif source=15438-704_Comb_Asmt_Dec#page6.tif source=15438-704_Comb_Asmt_Dec#page7.tif	

**COMBINED ASSIGNMENT & DECLARATION**

**ASSIGNMENT**

WHEREAS, **Seungwoo HONG, Jong Il PARK, Heechang OH, Yeongseop PARK, Dong Hee HAN, and Hyungbok LEE**, hereinafter called the "Assignors", have made the invention described in the United States patent application entitled **ENGINE SYSTEM AND METHOD USING THE SAME**, Executed by Assignors on the same date as, or on a date prior to, this Assignment;

WHEREAS, Hyundai Motor Company, a corporation organized and existing under the laws of Korea, having a place of business at 12, Heolleung-ro, Seocho-gu, Seoul 06797, Republic of Korea and KIA Motors Corporation of 12, Heolleung-ro, Seocho-gu, Seoul 06797, Republic of Korea, hereinafter called the "Assignee", desire to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, be it known that, for good and valuable consideration the receipt of which by the Assignors from Assignee is hereby acknowledged, the Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer to the Assignee, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents issuing therefrom in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; together with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignors hereby covenant and agree, for both the Assignors and the Assignors' legal representatives, that the Assignors will assist the Assignee in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignee may elect to make covering the invention identified above; in vesting in the Assignee like exclusive title in and to all such other patent applications and patents; and that the Assignors will execute and deliver to the Assignee any and all additional papers which may be requested by the Assignee to carry out the terms of this Assignment.

The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignors have executed this agreement.

**DECLARATION**

As the below-named inventor, I hereby declare that:

This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to the patentability of this application as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Further, I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application and any patent issued thereon.

DATE: Oct. 11, 2018

SIGNATURE: Seungwoo Hong  
Seungwoo HONG

**DECLARATION**

As the below-named inventor, I hereby declare that:

This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

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DATE: Oct 11 2018

SIGNATURE: Jong Il PARK

DECLARATION

As the below-named inventor, I hereby declare that:

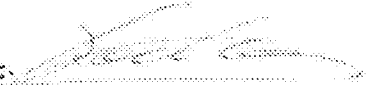
This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

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DATE: Oct 11, 2018

SIGNATURE:   
Heechang OH

**DECLARATION**

As the below-named inventor, I hereby declare that:

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DATE: 04 11 2018

SIGNATURE: Yeongseop Park  
Yeongseop PARK

DECLARATION

As the below-named inventor, I hereby declare that:


This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

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DATE: Oct. 11 2018

SIGNATURE:   
Dong Hee HAN



DECLARATION

As the below-named inventor, I hereby declare that:


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DATE: Oct. 11, 2018

SIGNATURE:   
Hyungbok LEE